

#### **DESCRIPTION**

The 6N135, 6N136, ICPL4502 and ICPL4503 devices each consists of an infrared emitting diode, optically coupled to a high speed photo detector transistor. A separate connection for the photodiode bias and output-transistor collector increases the speed by several orders of magnitude over conventional phototransistor couplers by reducing the base-collector capacitance of the input transistor.

#### **FEATURES**

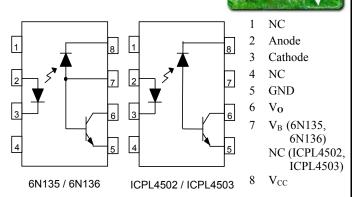
- High speed 1Mbit/s
- High AC Isolation Voltage 5000V<sub>rms</sub>
- Guaranteed performance from 0°C to 70°C
- Wide Operating temperature range -55°C to 100°C
- Pb Free and RoHS Compliant
- UL File E91231
- VDE Approval Certificate No. 40044376 for 6N135 and 6N136, with suffix "V"

#### **APPLICATIONS**

- Line Receivers
- Telecommunication Equipments
- Power Transistor Isolation in Motor Drives
- Replacement of Low Speed Phototransistor Optocouplers
- Feedback Loop in Switch Mode Power Supplies
- High Speed Logic Ground Isolation
- Home Appliances

#### ORDER INFORMATION

- Add G after PN for 10mm lead spacing
- Add SM after PN for Surface Mount
- Add SMT&R after PN for Surface Mount Tape & Reel



A 0.1 $\mu$ F bypass Capacitor shall be connected between  $V_{CC}$  and GND.

#### ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device.

Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

#### Input

Forward Current	25mA
Forward Peak Current (50% duty cycle, 1ms pulse width)	50mA
Peak Transient Current (≤1µs pulse width, 300pps)	1A
Reverse Voltage	5V
Power dissipation	45mW

#### Output

Output Current	8mA
Peak Output Current	16mA
Emitter-Base Reverse Voltage (6N135 and 6N136)	5V
Base Current (6N135 and 6N136)	5mA
Supply Voltage	-0.5V to 30V
Output Voltage	-0.5V to 20V
Power Dissipation	100mW

#### **Total Package**

•	
Isolation Voltage	$5000V_{\text{RMS}}$
Operating Temperature	-55 to 100 °C
Storage Temperature	-55 to 125 °C
Lead Soldering Temperature (10s)	260°C

#### **ISOCOM COMPONENTS 2004 LTD**

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## **ELECTRICAL CHARACTERISTICS** ( $T_A = 0$ °C to 70°C unless otherwise specified)

### **INPUT**

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Forward Voltage	$V_{\mathrm{F}}$	$I_F = 16mA$		1.45	1.8	V
Reverse Voltage	$V_R$	$I_R = 10\mu A$	5.0			V
Forward Voltage Temperature Coefficient	$\Delta V_F/\Delta T_A$	$I_F = 16mA$		-1.9		mV/°C

### **OUTPUT**

Parameter	Symbol	Test Condition	Min	Typ.*	Max	Unit
Logic High Output Current	$I_{OH}$	$I_F = 0$ mA, $V_O = V_{CC} = 5.5$ V, $T_A = 25$ °C		0.001	0.5	μΑ
		$I_F = 0$ mA, $V_O = V_{CC} = 15$ V, $T_A = 25$ °C		0.01	1	
		$I_F = 0 \text{mA}, V_O = V_{CC} = 15 \text{V}$			50	]
Logic Low Output Voltage	V <sub>OL</sub>	$I_F = 16\text{mA}, \ I_O = 1.1\text{mA}, \ V_{CC} = 4.5\text{V}, \ T_A = 25^{\circ}\text{C}$		0.18	0.4	V
		$I_F = 16\text{mA}, \ I_O = 0.8\text{mA}, \ V_{CC} = 4.5\text{V},$			0.5	
		$\begin{aligned} & 6\text{N}136 \text{ / ICPL}4502 \text{ / ICPL}4503} \\ & & I_F = 16\text{mA}, \ I_O = 3\text{mA}, \\ & & V_{CC} = 4.5\text{V}, \ T_A = 25^{\circ}\text{C} \end{aligned}$		0.25	0.4	
		$I_F = 16\text{mA}, I_O = 2.4\text{mA},$ $V_{CC} = 4.5\text{V}$			0.5	
Logic Low Supply Current	$I_{CCL}$	$I_F = 16\text{mA}, V_O = \text{Open},$ $V_{CC} = 15\text{V}$		140	200	μА
Logic High Supply Current	$I_{CCH}$	$I_F = 0$ mA, $V_O = 0$ pen, $V_{CC} = 15$ V, $T_A = 25$ °C		0.01	1	μА
		$I_F = 0$ mA, $V_O = O$ pen, $V_{CC} = 15V$			2	

<sup>\*</sup> Typical values at  $T_A$  = 25°C



## **ELECTRICAL CHARACTERISTICS** ( $T_A = 0$ °C to 70°C unless otherwise specified)

### **COUPLED**

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Current Transfer Ratio	CTR	6N135	7		50	%
		6N136 / ICPL4502 / ICPL4503	19		50	
		$I_F = 16\text{mA}, V_O = 0.4\text{V}$ $V_{CC} = 4.5\text{V}, T_A = 25^{\circ}\text{C}$				
		6N135	5			
		6N136 / ICPL4502 / ICPL4503	15			
		$I_F = 16\text{mA}, V_O = 0.5\text{V}$ $V_{CC} = 4.5\text{V}$				

### **ISOLATION**

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Insulation Voltage	$V_{\rm ISO}$	$T_A = 25$ °C, RH = 40 % to 60%, t = 1 min,	5000			$V_{RMS}$

<sup>\*</sup> Typical values at  $T_A = 25$ °C



## **ELECTRICAL CHARACTERISTICS** ( $T_A = 0$ °C to 70°C unless otherwise specified)

Switching Characteristics ( $T_A = 0$ °C to 70°C,  $I_F = 16$ mA,  $V_{CC} = 5$ V unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур.*	Max	Unit
Propagation Delay Time	$T_{PHL}$	6N135				μs
to Logic Low		$R_{L} = 4.1k\Omega, T_{A} = 25^{\circ}C$ $R_{L} = 4.1k\Omega$		0.35	1.5 2.0	
		6N136 / ICPL4502 / ICPL4503				
		$R_{L} = 1.9k\Omega, T_{A} = 25^{\circ}C$ $R_{L} = 1.9k\Omega$		0.35	0.8 1.0	
Propagation Delay Time	$T_{PLH}$	6N135				μs
to Logic High		$R_L = 4.1k\Omega, T_A = 25^{\circ}C$ $R_L = 4.1k\Omega$		0.5	1.5 2.0	
		6N136 / ICPL4502 / ICPL4503				
		$R_{L} = 1.9k\Omega, T_{A} = 25^{\circ}C$ $R_{L} = 1.9k\Omega$		0.3	0.8 1.0	
Common Mode Tran-	CM <sub>H</sub>	6N135	1000			V/µs
sient Immunity at Logic High		$I_F = 0 \text{mA}, V_{CM} = 10 \text{Vp-p},$ $R_L = 4.1 \text{k}\Omega, T_A = 25 ^{\circ}\text{C}$				
		6N136 / ICPL4502	1000			
		$I_F = 0 \text{mA}, V_{CM} = 10 \text{Vp-p},$ $R_L = 1.9 \text{k}\Omega, T_A = 25 ^{\circ}\text{C}$				
		ICPL4503	15000	20000		
		$I_F = 0 \text{mA}, V_{CM} = 1500 \text{Vp-p},$ $R_L = 1.9 \text{k}\Omega, T_A = 25^{\circ}\text{C}$				
Common Mode Tran-	$CM_L$	6N135	1000			V/µs
sient Immunity at Logic Low		$I_F = 16\text{mA}, V_{CM} = 10\text{Vp-p},$ $R_L = 4.1\text{k}\Omega, T_A = 25^{\circ}\text{C}$				
		6N136 / ICPL4502	1000			
		$I_F = 16\text{mA}, V_{CM} = 10\text{Vp-p},$ $R_L = 1.9\text{k}\Omega, T_A = 25^{\circ}\text{C}$				
		ICPL4503	15000	20000		
		$I_F = 16\text{mA}, V_{CM} = 1500\text{Vp-p},$ $R_L = 1.9\text{k}\Omega, T_A = 25^{\circ}\text{C}$				

<sup>\*</sup> Typical values at  $T_A = 25$ °C



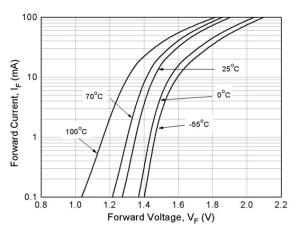


Fig 1 Forward Current vs Forward Voltage

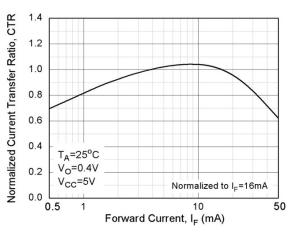


Fig 3 Normalized CTR vs Forward Current

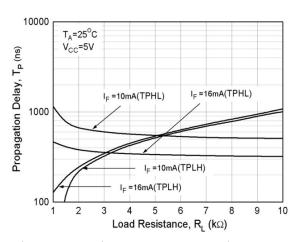


Fig 5 Propagation Delay vs Load Resistance

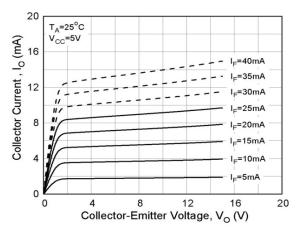


Fig 2 Output Current vs Output Voltage

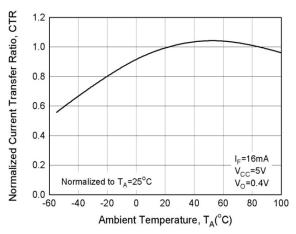


Fig 4 Normalized CTR vs T<sub>A</sub>

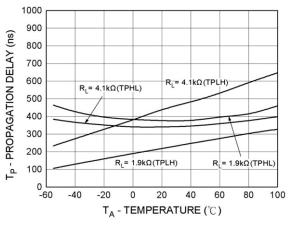


Fig 6 Propagation Delay vs TA



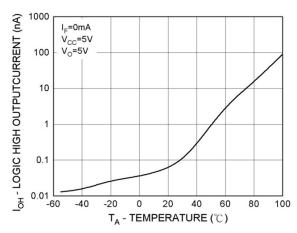
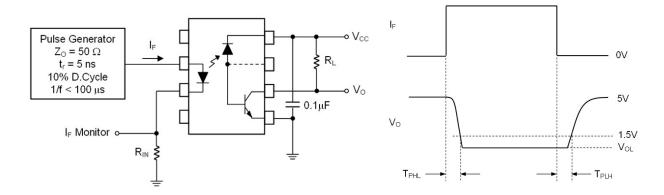
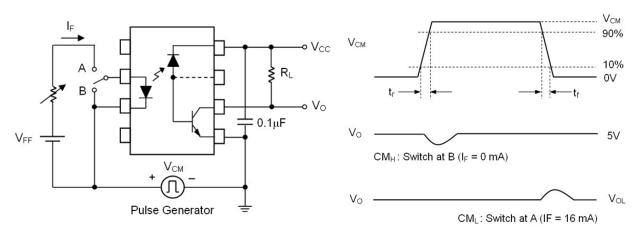


Fig 7 Logic High Output Current vs TA



**Switching Time Test Circuit** 





**Common Mode Transient Immunity Test Circuit** 

#### Note:

Common mode transient immunity in logic high level is the maximum tolerable (positive)  $dV_{CM}/dt$  on the leading edge of the common mode pulse signal  $V_{CM}$ , to assure that the output will remain in a logic high state (i.e.,  $V_O > 2.0V$ ).

Common mode transient immunity in logic low level is the maximum tolerable (negative)  $dV_{CM}/dt$  on the trailing edge of the common mode pulse signal,  $V_{CM}$ , to assure that the output will remain in a logic low state (i.e.,  $V_O < 0.8V$ ).

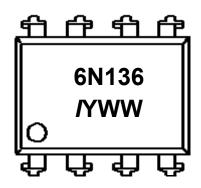


### **ORDER INFORMATION**

6N135, 6N136, ICPL4502, ICPL4503 (UL Approval)						
After PN	PN	Description	Packing quantity			
None	6N135, 6N136, ICPL4502, ICPL4503	Standard Dip8	45 pcs per tube			
G	6N135G, 6N136G, ICPL4502G, ICPL4503G	10mm Lead Spacing	45 pcs per tube			
SM	6N135SM, 6N136SM, ICPL4502SM, ICPL4503SM	Surface Mount	45 pcs per reel			
SMT&R	6N135SMT&R, 6N136SMT&R, ICPL4502SMT&R, ICPL4503SMT&R	Surface Mount Tape & Reel	1000 pcs per reel			

	6N135V, 6N136V (UL and VDE Approvals)					
After PN	PN	Description	Packing quantity			
None	6N135V, 6N136V	Standard Dip8	45 pcs per tube			
G	6N135VG, 6N136VG	10mm Lead Spacing	45 pcs per tube			
SM	6N135VSM, 6N136VSM	Surface Mount	45 pcs per reel			
SMT&R	6N135VSMT&R, 6N136VSMT&R	Surface Mount Tape & Reel	1000 pcs per reel			

## **DEVICE MARKING (Example: 6N136)**



6N136 denotes Device Part Number

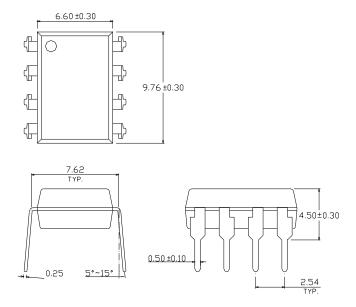
Y denotes 1 digit Year code WW denotes 2 digit Week code

I denoted Isocom

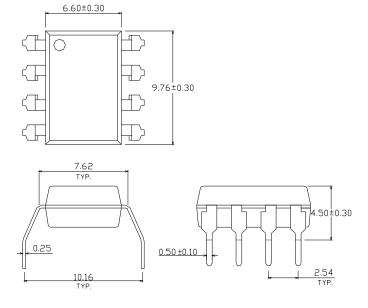


## **PACKAGE DIMENSIONS (mm)**

DIP



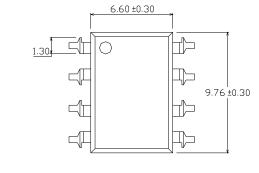
### **G-Form**

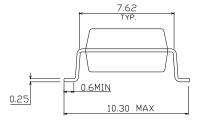


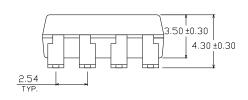


## **PACKAGE DIMENSIONS (mm)**

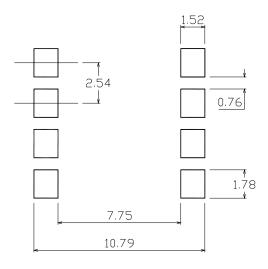
### **SMD**





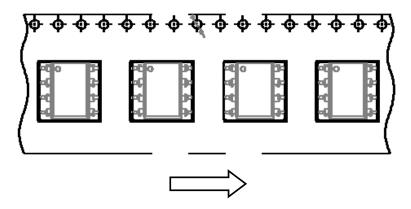


### **RECOMMENDED PAD LAYOUT FOR SMD (mm)**

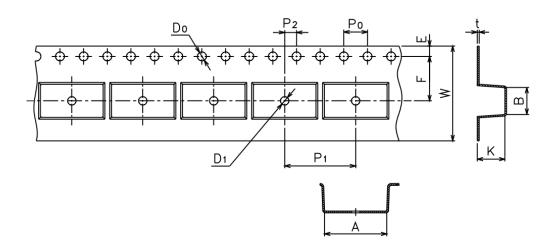




### **TAPE AND REEL PACKAGING**



### Direction of feed from reel

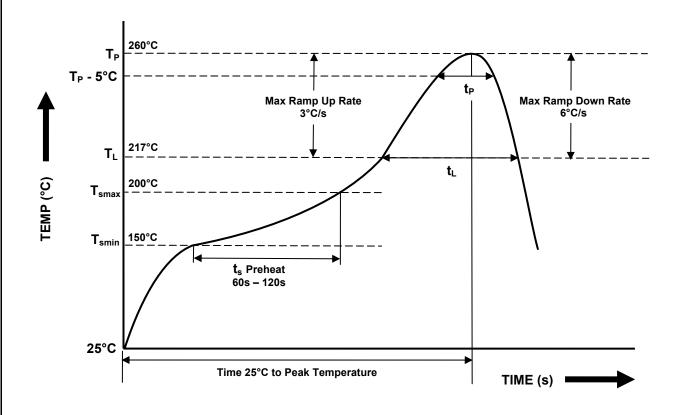


Dimension No.	Α	В	D <sub>0</sub>	D <sub>1</sub>	E	F
Dimension( mm)	10.4±0.1	10.0±0.1	1.5±0.1	1.5±0.1	1.75±0.1	7.5±0.1
Dimension No.	P <sub>0</sub>	P <sub>1</sub>	P <sub>2</sub>	t	w	К
Dimension (mm)	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0 ±0.3 / -0.1	4.5±0.1



### **REFLOW SOLDERING TEMPERATURE PROFILE**

(One Time Reflow Soldering is Recommended)

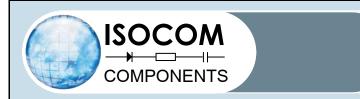


Profile Details	Conditions
$ \begin{array}{l} \textbf{Preheat} \\ \textbf{- Min Temperature } (T_{SMIN}) \\ \textbf{- Max Temperature } (T_{SMAX}) \\ \textbf{- Time } T_{SMIN} \text{ to } T_{SMAX} \left(t_s\right) \end{array} $	150°C 200°C 60s - 120s
$\begin{tabular}{ll} \textbf{Soldering Zone} \\ - & \mbox{Peak Temperature } (T_P) \\ - & \mbox{Liquidous Temperature } (T_L) \\ - & \mbox{Time within } 5^{\circ}\mbox{C of Actual Peak Temperature } (T_P - 5^{\circ}\mbox{C}) \\ - & \mbox{Time maintained above } T_L \ (t_L) \\ - & \mbox{Ramp Up Rate } (T_L \ \mbox{to } T_P) \\ - & \mbox{Ramp Down Rate } (T_P \ \mbox{to } T_L) \\ \end{tabular}$	260°C 217°C 30s 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate (T <sub>smax</sub> to T <sub>P</sub> )	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



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- When requiring a device for any "specific" application, please contact our sales for advice.
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- Do not immerse device body in solder paste.



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